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ABSTRACT OF THE INVENTION

- The present invention relates to a copper electroplating bath composition and method of
- 3 using it for microelectronic device fabrication. In particular, the present invention relates to
- 4 copper electroplating in the fabrication of interconnect structures in semiconductor devices. By
- 5 use of the inventive copper electroplating bath composition, the incidence of voids in the
- 6 interconnect structures is reduced.

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